Notification Number: 20200715000 Notification Date: July 21, 2020						
Title: Datasheet for LMV321, LMV324, L	_MV358					
Customer Contact: PCN Manager		De	pt: Quality Service	es		
Change Type:						
Assembly Site Design	gn		Wafer Bump Site			
☐ Assembly Process ☐ Data	Sheet		Wafer Bump Material			
Assembly Materials Part	number change		Wafer Bump Process			
Mechanical Specification Test	Site		Wafer Fab Site			
Packing/Shipping/Labeling Test	Process		Wafer Fab Materials			
			Wafer Fab Process			
Notification Details						
Description of Change:						
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.						
TEXAS INSTRUMENTS			LMV321, LMV324, LMV3	358		
INSTRUMENTS		SLOS	263X - AUGUST 1999-REVISED MAY	2020		
Changes from Revision W (October 2014) to Revision	x		Pag	e		
Deleted LMV324S mentions on the front page of the contractions.	lata sheet			1		
 Added end equipment links in Application section 				1		
 Added recommended device notice for LMV321A, LM 	V358A, and LMV324A			1		
· Changed Device Information table to sort devices by	channel count in ascending ord	der		1		
· Changed Pin Configuration and Functions section by	dividing the Pin Functions table	e into	separate tables per device	3		
Deleted LMV324S pinout information				4		
Changed HBM ESD voltage from 2500 V to 2000 V						
Changed CDM ESD voltage from 1500 V to 1000 V						
 Deleted Shutdown voltage threshold for LMV324S 	5					
Changed Thermal Information section by dividing the Thermal Information table into separate tables per device						
Changed Thermal Information for LMV321				5		
Deleted LMV324S Thermal Information						
Changed Thermal Information for LMV324						
Changed Thermal Information for LMV358						
Deleted LMV324S test condition for supply current						
Changed output short-circuit current for sourcing from 60 mA to 40 mA						
Changed output short-circuit current for sinking from 160 mA to 40 mA						
Deleted LMV324S test condition for supply current						
Added assured by characterization table notes to output short-circuit current, output swing, and input bias current specifications						
Changed Source Current Vs Output Voltage V _{cc} =2.7V plot with Output Voltage vs Output Current (Claw) plot in Typical Characteristics section						
Deleted plots Source Current Vs Output Voltage V _{CC} = 5V, Sinking Current vs Output Voltage V _{CC} =2.7V, Sinking Current vs Output Voltage V _{CC} =5V, Short-Circuit Current vs Temperature in <i>Typical Characteristics</i> section						
Changed Open-Loop Output Impedance Vs Frequency plot in Typical Characteristics section						
Added Receiving Notification and Support Resources sections to the Device and Documentation Support section						
The datasheet number will be changing.						
Device Family	Change From:		Change To:			
,	GLOCACAW GLOCACAY					
LMV321, LMV324, LMV358	SLOS263W		SLOS263X			

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/LMV321

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

	-		
LMV321IDBVR	LMV321IDBVRE4	LMV321IDBVRG4	LMV321IDBVT
LMV321IDBVTE4	LMV321IDCKR	LMV321IDCKRG4	LMV321IDCKT
LMV324ID	LMV324IDR	LMV324IDRE4	LMV324IDRG4
LMV324IPWR	LMV324IPWRE4	LMV324IPWRG4	LMV324QD
LMV324QDG4	LMV324QDR	LMV324QDRG4	LMV324QPW
LMV324QPWR	LMV324QPWRE4	LMV358ID	LMV358IDDUR
LMV358IDDURG4	LMV358IDG4	LMV358IDGKR	LMV358IDGKRG4
LMV358IDR	LMV358IDRE4	LMV358IPWG4	LMV358IDRG4
LMV358IPW	LMV358IPWR	LMV358IPWRE4	LMV358IPWRG4
LMV358QD	LMV358QDDUR	LMV358QDDURG4	LMV358QDG4
LMV358QDGKR	LMV358QDGKRG4	LMV358QDR	LMV358QPWR

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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